### 54AC16373, 74AC16373 16-BIT TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

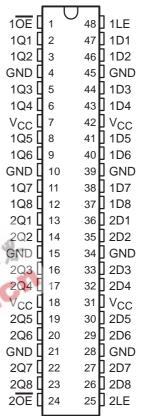
SCAS121B - MARCH 1990 - REVISED APRIL 1996

- Members of the Texas Instruments Widebus™ Family
- 3-State True Outputs
- Full Parallel Access for Loading
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

### description

The 'AC16373 are 16-bit transparent D-type latches with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. The device can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

54AC16373 . . . WD PACKAGE 74AC16373 . . . DL PACKAGE (TOP VIEW)



A buffered output-enable  $(\overline{OE})$  input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.  $\overline{OE}$  does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74AC16373 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16373 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16373 is characterized for operation from –40°C to 85°C.



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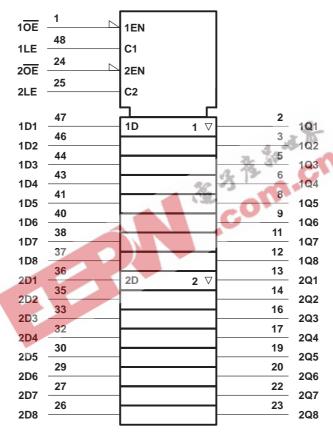


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### **FUNCTION TABLE**

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q <sub>0</sub>
Н	Χ	Χ	Z

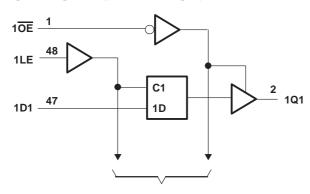
## logic symbol†

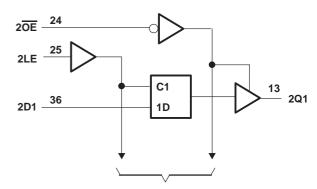


<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## 54AC16373, 74AC16373 **16-BIT TRANSPARENT D-TYPE LATCHES** WITH 3-STATE OUTPUTS SCAS121B - MARCH 1990 - REVISED APRIL 1996

### logic diagram (positive logic)





To Seven Other Channels

To Seven Other Channels

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V <sub>O</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±400 mA
Maximum power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T <sub>Stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

# 54AC16373, 74AC16373 **16-BIT TRANSPARENT D-TYPE LATCHES** WITH 3-STATE OUTPUTS SCAS121B - MARCH 1990 - REVISED APRIL 1996

### recommended operating conditions (see Note 3)

			54	AC1637	'3	74	AC1637	'3	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
VCC	Supply voltage		3	5	5.5	3	5	5.5	V
		V <sub>CC</sub> = 3 V	2.1			2.1			
$V_{\text{IH}}$	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V
		$V_{CC} = 5.5 \text{ V}$	3.85			3.85			
		V <sub>CC</sub> = 3 V			0.9			0.9	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 4.5 V		1/2	1.35			1.35	V
		V <sub>CC</sub> = 5.5 V		J.	1.65			1.65	
VI	Input voltage		0	Q	VCC	0		VCC	V
٧o	Output voltage		0	Ú	VCC	0		VCC	V
		VCC = 3 V	10	)	-4			-4	
ІОН	High-level output current	V <sub>CC</sub> = 4.5 V	200		-24			-24	mA
		V <sub>CC</sub> = 5.5 V			-24			-24	
		V <sub>CC</sub> = 3 V			12			12	
IOL	Low-level output current	V <sub>CC</sub> = 4.5 V		3	24			24	mA
		V <sub>CC</sub> = 5.5 V	25-		24			24	
Δt/Δν	Input transition rise or fall rate		0	, ,	10	0		10	ns/V
TA	Operating free-air temperature	- X	-55	S	125	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V	T,	Δ = 25°C	54AC1637	74AC	16373	UNIT
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP MAX	MIN MA	X MIN	MAX	UNII
		3 V	2.9		2.9	2.9		
	I <sub>OH</sub> = -50 μA	4.5 V	4.4		4.4	4.4		
		5.5 V	5.4		5.4	5.4		
Voн	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.48	2.48		V
	lo: - 24 mA	4.5 V	3.94		3.8	3.8		
	I <sub>OL</sub> = -24 mA	5.5 V	4.94		4.8	4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V			3.85	3.85		
		3 V		0.1	20	.1	0.1	
	I <sub>OL</sub> = 50 μA	4.5 V		0.1	50	.1	0.1	
		5.5 V		0.1	000	.1	0.1	
VOL	I <sub>OL</sub> = 12 mA	3 V		0.36	0.4	14	0.44	V
	lo: = 24 mA	4.5 V		0.36	0.4	14	0.44	
	I <sub>OL</sub> = 24 mA	5.5 V		0.36	0.4	14	0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V			1.0	35	1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V		±0.1	:	<u>-</u> 1	±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V		±0.5	-	±5	±5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		8	1	30	80	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		4.5				pF
Co	$V_O = V_{CC}$ or GND	5 V		12				pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



## 54AC16373, 74AC16373 16-BIT TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCAS121B - MARCH 1990 - REVISED APRIL 1996

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

		T <sub>A</sub> = :	25°C	54AC1	6373	74AC1	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t <sub>W</sub>	Pulse duration, LE high	5		5	100	5		ns
t <sub>su</sub>	Setup time, data before LE↓	1.5		1.5	11/2	1.5		ns
t <sub>h</sub>	Hold time, data after LE↓	3		3		3		ns

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

		T <sub>A</sub> = 25°C	54AC16373	74AC16373	UNIT
		MIN MA	X MIN MAX	MIN MAX	ONIT
t <sub>W</sub>	Pulse duration, LE high	4	4 10 11	4	ns
t <sub>su</sub>	Setup time, data before LE↓	1.5	1.5	1.5	ns
t <sub>h</sub>	Hold time, data after LE↓	2.5	2.5	2.5	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	- %f	A = 25°C	C	54AC1	6373	74AC1	6373	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	D	Q	3.7	10.6	13.4	3.7	15.1	3.7	15.1	nc
<sup>t</sup> PHL	Ь	· ·	4.3	11.3	14	4.3	14.8	4.3	14.8	ns
<sup>t</sup> PLH	LE	Q	4.6	12.9	15.8	4.6	18.6	4.6	18.6	ns
<sup>t</sup> PHL	LL	ď	4.5	12.1	14.6	4.5	16.4	4.5	16.4	115
<sup>t</sup> PZH	ŌĒ	Q	4.2	11.8	14.8	4.2	17.5	4.2	17.5	ns
t <sub>PZL</sub>	OE	γ	5.4	16.3	19.8	5.4	22.3	5.4	22.3	115
<sup>t</sup> PHZ	ŌĒ	Q	4.2	7.9	9.5	4.2	10.2	4.2	10.2	ns
<sup>t</sup> PLZ	OE .	ά	3.8	7.1	8.9	3.8	9.8	3.8	9.8	115

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

				,						
PARAMETER	FROM	то	TO $T_A = 25^{\circ}C$		;	54AC1	6373	74AC1	6373	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
t <sub>PLH</sub>	D	Q	3.1	6.7	8.5	3.1	9.7	3.1	9.7	20
t <sub>PHL</sub>			3.5	7.3	9.1	3.5	10/1	3.5	10.1	ns
t <sub>PLH</sub>	LE	Q	3.8	8.2	10.2	3.8	11.9	3.8	11.9	ns
t <sub>PHL</sub>		Q Q	3.6	7.8	9.7	3.6	10.9	3.6	10.9	113
<sup>t</sup> PZH	ŌĒ	Q	3.5	7.4	9.4	3.5	10.8	3.5	10.8	ns
<sup>t</sup> PZL	OE	ď	4.3	9.1	11.3	4.3	12.8	4.3	12.8	115
<sup>t</sup> PHZ	ŌĒ	Q	3.9	6.6	8	3.9	8.8	3.9	8.8	ne
t <sub>PLZ</sub>	OE	ų ų	3.7	5.9	7.4	3.7	8.1	3.7	8.1	ns

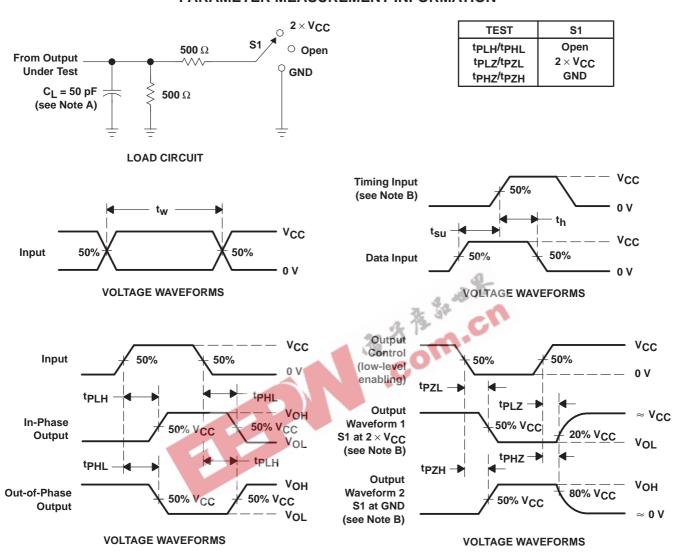
## operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CON	TYP	UNIT		
C .	Dower discinction conscitance per letch	Outputs enabled	C: - 50 pE	f = 1 MHz	43	pF
Cpd	Power dissipation capacitance per latch	Outputs disabled	C <sub>L</sub> = 50 pF,	I = I IVIDZ	5	pΓ

## 54AC16373, 74AC16373 **16-BIT TRANSPARENT D-TYPE LATCHES** WITH 3-STATE OUTPUTS

SCAS121B - MARCH 1990 - REVISED APRIL 1996

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 3 \ ns$ ,  $t_f = 3 \ ns$ .
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





### PACKAGE OPTION ADDENDUM

24-Feb-2006

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74AC16373DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC16373DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC16373DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC16373DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): Ti's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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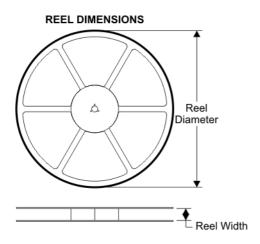
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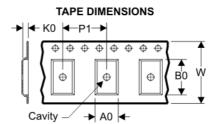


## **PACKAGE MATERIALS INFORMATION**

4-Oct-2007

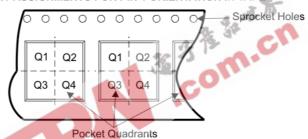
### TAPE AND REEL BOX INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPES

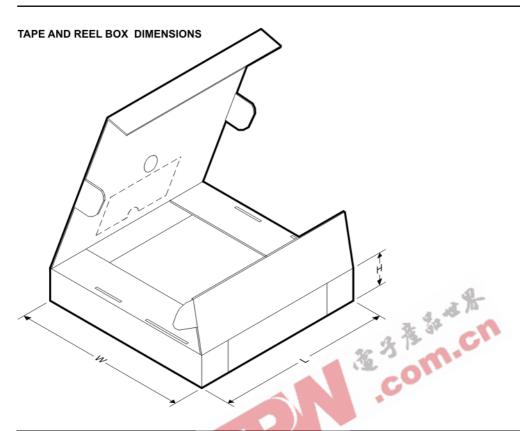


Device	Pack	age	Pins		Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AC16373DLR	DL	. 🔻	48	SITE 41	330	32	11.35	16.2	3.1	16	32	Q1





4-Oct-2007

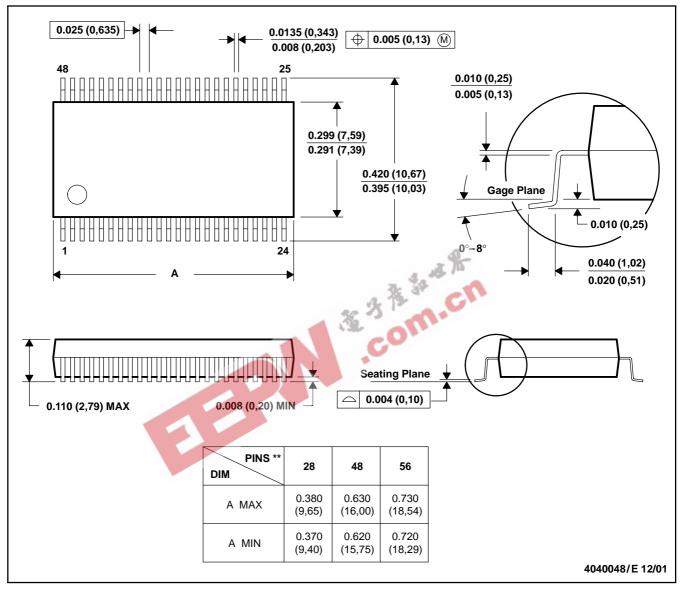


Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
74AC16373DLR	DL .	48	SITE 41	346.0	346.0	49.0

### DL (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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